

ISSUE: [March 2020](#)

### ***International 3D-PEIM Symposium Postponed Until June 2021***

[The International 3D Power Electronics Integration and Manufacturing \(3D-PEIM\) Symposium](#), which was initially planned for June 2020 at Osaka University, Japan has been postponed due to the Coronavirus threat until June 21-23, 2021 at Osaka University.

The 3D-PEIM 2020 Steering Team met last Friday to realistically assess the possible impact that the COVID-19 (Coronavirus) would have on our June 2020 Symposium. Presently there are many companies, universities, and countries banning travel. We expect that it may most likely become worse. Since we felt that we do not know what the situation will be in three months or six months, our decision is to postpone our Third Biennial 3D-PEIM Symposium until June 21–23, 2021.

We remain committed to holding the symposium at Osaka University in Japan on our new date. Thanks to the speakers, session chairs, and members of the technical program committee and steering committee that have worked hard and contributed to building an excellent technical program. We want to retain our original program if possible. So we are encouraging those committed to our previous June 2020 event to remain committed to or to re-commit to our postponed 3D-PEIM Symposium in 2021. We intentionally set a firm date so that you could plan appropriately once the crisis is over.

In the meantime, we are going to leave the symposium website open and will provide updates as they become available, probably starting this fall. You can check progress at <http://3d-peim.org/>. We will retain all partners and sponsors on the website if they so choose.